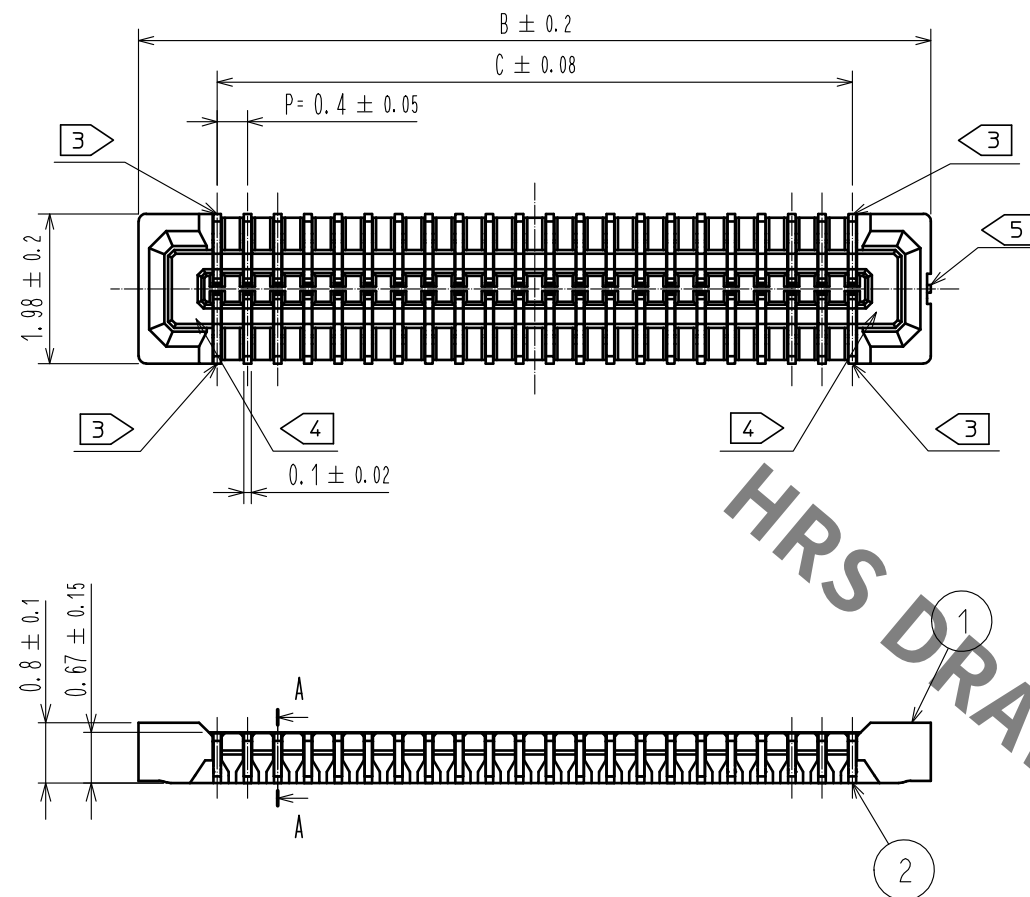
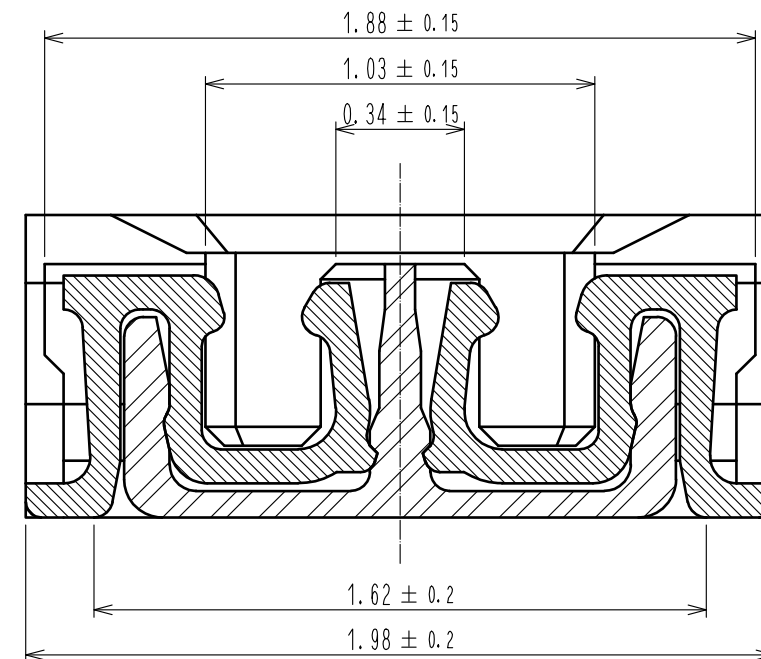




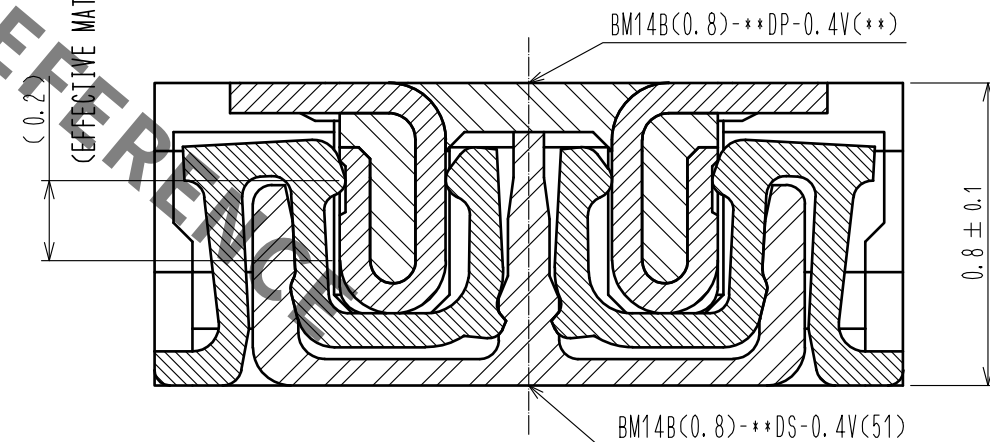
- NOTE) 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μ m MIN
SMT LEAD : GOLD 0.05 μ m MIN
UNDERPLATING : NICKEL 1 μ m MIN
(SURFACE : SEALING)
3. EACH CONTACTS AT 4 CORNERS ARE PROVIDED FOR METAL FITTINGS AND GROUNDING PURPOSE.
4. HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.
5. GATE POSITION IS INDICATED IN APPROX POSITION SHOWN.

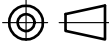
PART No.	CODE No.	B	C
BM14B(0.8)-10DS-0.4V(51)	CL684-8003-5-51	4.48	2.4
BM14B(0.8)-12DS-0.4V(51)	CL684-8041-4-51	4.88	2.8
BM14B(0.8)-20DS-0.4V(51)	CL684-8004-8-51	6.48	4.4
BM14B(0.8)-22DS-0.4V(51)	-	6.88	4.8
BM14B(0.8)-24DS-0.4V(51)	CL684-8005-0-51	7.28	5.2
BM14B(0.8)-30DS-0.4V(51)	CL684-8006-3-51	8.48	6.4
BM14B(0.8)-34DS-0.4V(51)	CL684-8007-6-51	9.28	7.2
BM14B(0.8)-40DS-0.4V(51)	CL684-8008-9-51	10.48	8.4
BM14B(0.8)-50DS-0.4V(51)	CL684-8009-1-51	12.48	10.4
BM14B(0.8)-60DS-0.4V(51)	CL684-8001-0-51	14.48	12.4

A-A (50:1)

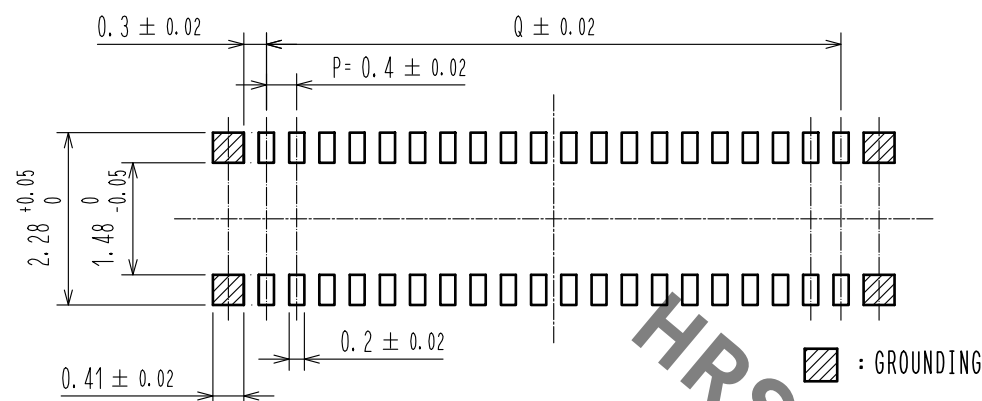


ENGAGEMENT FIGURE (50:1)



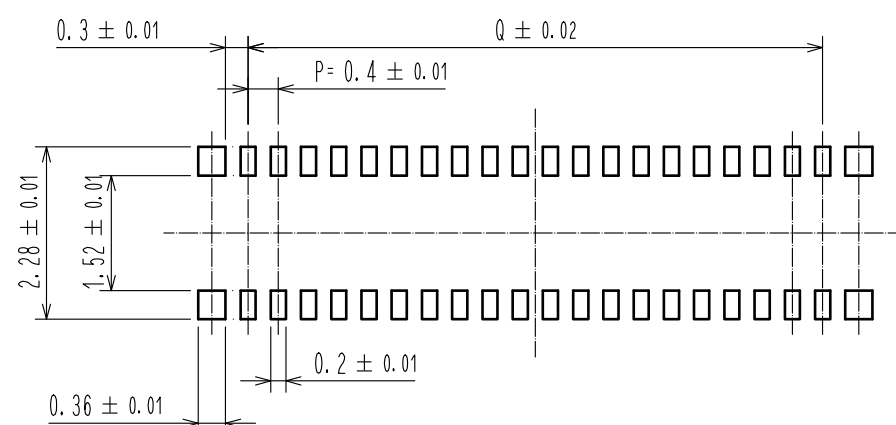
3	PS	CLEAR (ENBOSSED CARRIER TAPE)		6	PS	CLEAR (REINFORCEMENT COLLAR)			
2	PHOSPHOR BRONZE	2		5	PS	BLACK (PLASTIC REEL)			
1	LCP	UL94 V-0, BLACK		4	POLYESTER	CLEAR (COVER TAPE)			
NO.	MATERIAL	FINISH . REMARKS		NO.	MATERIAL	FINISH . REMARKS			
UNITS mm		SCALE 10 : 1		COUNT 1	DESCRIPTION OF REVISIONS DIS-H-00003048		DESIGNED NY. YAMASHIRO	CHECKED TS. MIYAZAKI	DATE 17. 09. 29
 HIROSE ELECTRIC CO., LTD.		APPROVED : KH. IKEDA			09. 11. 24		DRAWING NO. EDC3-322327-04		
		CHECKED : WR. FUKUCHI			09. 11. 24		PART NO. BM14B(0.8) - *DS-0.4V(51)		
		DESIGNED : YH. HASEGAWA			09. 11. 20		CODE NO. CL684		
		DRAWN : YH. HASEGAWA			09. 11. 20		 1/3		

◆ RECOMMENDED PCB LAYOUT



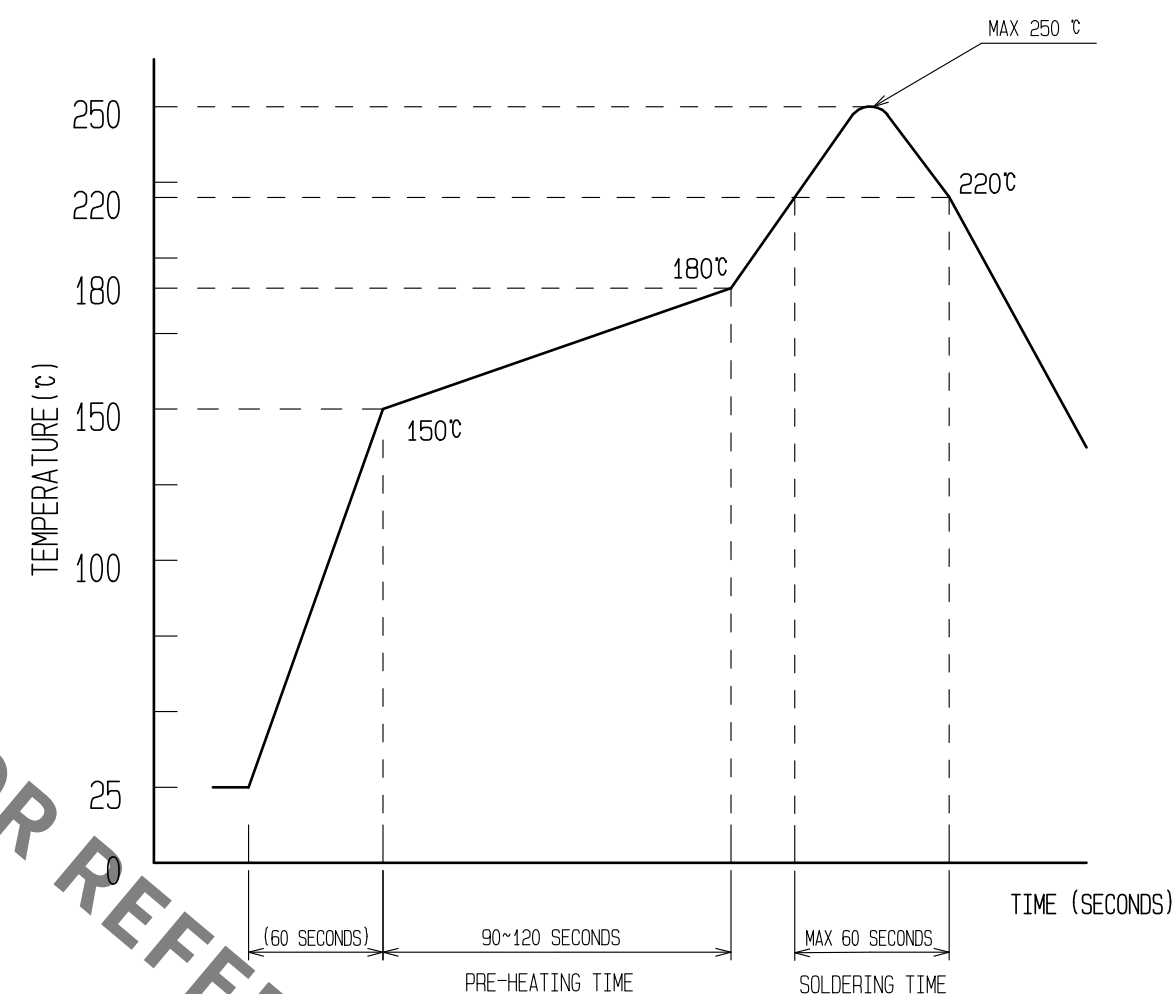
◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μm



PART No.	Q
BM14B(0.8)-10DS-0.4V(51)	1.6
BM14B(0.8)-12DS-0.4V(51)	2.0
BM14B(0.8)-20DS-0.4V(51)	3.6
BM14B(0.8)-22DS-0.4V(51)	4.0
BM14B(0.8)-24DS-0.4V(51)	4.4
BM14B(0.8)-30DS-0.4V(51)	5.6
BM14B(0.8)-34DS-0.4V(51)	6.4
BM14B(0.8)-40DS-0.4V(51)	7.6
BM14B(0.8)-50DS-0.4V(51)	9.6
BM14B(0.8)-60DS-0.4V(51)	11.6

⑥ RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

- 1) REFLOW TIME
DURATION ABOVE 220°C, 60 SEC. MAX.
(PEAK TEMPERATURE: 250°C MAX)
- 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 sec.

⑥ THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC3-322327-04
PART NO.	BM14B(0.8)-*DS-0.4V(51)
CODE NO.	CL684

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